



Docket No.: 20136-00344-US
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Vincent J. McGahay ✓

Application No.: 09/849,530 ~

Filed: May 7, 2001

For: METHOD FOR IMPROVING ADHESION TO
COPPER

Group Art Unit: 2823

Examiner: MALDONADO, J. L. 3/1/03

AMENDMENT

Box Non-Fee Amendment

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated December 4, 2002 (Paper No. 10), please amend the above-identified U.S. Patent application as follows:

REMARKS/ARGUMENTS

Claims 15-30 are now in the application. The indication that claims 18, 19 and 22-25 contain allowable subject matter is hereby noted.

Claims 15-17, 20, 21 and 26-29 were rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent 6,153,523 to Van Ngo, *et al.* (hereinafter also Van Ngo) in view of U.S. Patent 5,420,069 to Joshi, *et al.* (hereinafter also Joshi). The cited references fail to render obvious the present invention. According to the present invention, a layer(s) of copper germanide, germanium oxide and/or germanium nitride is provided on a surface of a copper member to improve the adhesion of another layer to the copper or copper alloy.

Van Ngo fails to suggest the present invention since, among other things, Van Ngo does not even remotely suggest improving a germanium layer for improving adhesion. The only

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